


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/22/13757	
<b>1.3 Title of PCN</b>	DPAK Automotive AI wire line relocation from Shenzhen to Tongfu Microelectronics (China)	
<b>1.4 Product Category</b>	Power MOSFET HV	
<b>1.5 Issue date</b>	2022-11-07	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	KRAUSE INA
<b>2.1.2 Phone</b>	+49 89460062370
<b>2.1.3 Email</b>	ina.krause@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Maurizio GIUDICE
<b>2.1.2 Marketing Manager</b>	Paolo PETRALI
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Shenzhen (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	DPAK Automotive AI wire products are manufactured in Shenzhen (China)	DPAK Automotive AI wire products are manufactured in Tongfu Microelectronics (China)
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	DPAK AI wire Automotive Line Shenzhen closure
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	By internal traceability and dedicated FG code
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-11-03
<b>7.2 Intended start of delivery</b>	2023-05-08
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13757 RERPTD22094_2.0_Power Mosfet High Voltage DPAK Automotive Transfer from STS to TFME.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-11-07

**9. Attachments (additional documentations)**

13757 Public product.pdf  
13757 DPAK Automotive AI wire line relocation from Shenzhen to TFME.pdf  
13757 RERPTD22094\_2.0\_Power Mosfet High Voltage DPAK Automotive Transfer from STS to TFME.pdf  
13757 PCN-FORM-Rev\_4\_0 Conti.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD15N50M2AG	
	STD18NF25	
	STD4NK100Z	
	STD7ANM60N	
	STD14NM50NAG	
	STD8NF25	

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